

Title (en)
INSTALLING AN ELECTRONIC ASSEMBLY

Title (de)
MONTAGE EINER ELEKTRONISCHEN BAUGRUPPE

Title (fr)
INSTALLATION D'ENSEMBLE ÉLECTRONIQUE

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Application
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Abstract (en)
[origin: WO2021018461A1] The invention relates to a method for installing an electronic assembly (10), having at least one die (40) and a substrate (150) with a conductive surface (152). The aim of the invention is to simplify the electric contacting of the dies during installation. This is achieved by the following step: arranging molded parts (21,..., 24), joining materials (30), and the at least one die (40) such that - the die (40) is electrically contacted by at least one of the molded parts (21,..., 24) and one of the joining materials (30) and - multiple functional elements (61, 62, 63) are formed from the molded parts (21,..., 24) and/or the die (40) and the joining materials (30), said functional elements being designed to support the substrate (150) and electrically contact the conductive surface (152). The invention additionally relates to an electronic assembly (10).

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